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To the Honorable Commissioner of … attached original documents or copy thereof.

1. Name of conveying party(ies)

2·3·04

Motoki KATO, Masanobu NAKAMURA, Kazuhiko NAKAMURA, Tomotaka YAGI, Declan Patrick KELLY, Wilhelmus Jacobus VAN GESTEL

Additional name(s) of conveying party(ies) attached? ___ Yes X No

2. Name and address of receiving party(ies)

Name:
SONY CORPORATION
7-35 Kitashinagawa 6-chome
Shinagawa-Ku, Tokyo 141-0001, Japan

MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD.
1006, Ooza Kadoma, Kadoma-shi,
Osaka 571-8501, Japan

KONINKLIJKE PHILIPS ELECTRONICS N.V.
Groenewoudseweg 1, 5621 BA Eindhoven,
The Netherlands

Additional name(s) & address(es) attached? ___ Yes x No

3. Nature of conveyance:

X Assignment
___ Security Agreement
___ Merger
___ Change of Name
___ Other

Execution Date: June 30, June 25, June 30, June 26, July 25 and July 28, 2003

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4. Application number(s) or patent number(s):

If this document is being filed together with a new application, the execution date of the application is:

A. USSN 10/470,312

Additional numbers attached? ___ Yes X No

5. Name and address of party to whom correspondence concerning document should be mailed:

Name: WILLIAM S. FROMMER
Internal Address: FROMMER LAWRENCE & HAUG LLP
Street Address: 745 FIFTH AVENUE
City: NEW YORK State: N.Y. Zip: 10151

6. Total number of applications and patents involved 1

7. Total fee (37 CFR 3.41) . . . . $ 40.00
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J:\SONY\04276\PCTMSPRT.COM (WSF:sar)

FLH File No.

ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

√ **INFORMATION PROCESSING METHOD AND APPARATUS, PROGRAM STORAGE MEDIUM, PROGRAM AND INFORMATION RECORDING MEDIUM**

for which application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 7-35, Kitashinagawa 6-chome, Shinagawa-ku, Tokyo 141-0001 Japan, MATSUSHITA ELECTRIC INDUSTRIAL CO., LTD., a Japanese corporation, with offices at 1006, Oaza Kadoma, Kadoma-shi, Osaka 571-8501 Japan, and KONINKLIJKE PHILIPS ELECTRONICS N.V., a Dutch corporation, with offices at Groenewoudseweg 1, 5621 BA Eindhoven, The Netherlands (hereinafter referred to as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar ($1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow: International Serial Number: **PCT/JP02/12560**, International Filing Date: **29 November 2002**.

This assignment executed on the dates indicated below.

Motoki KATO

Name of first or sole inventor — Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of first or sole inventor

Motoki Kato — 30th June 2003

Signature of first or sole inventor — Date of this assignment

Masanobu NAKAMURA

Name of second inventor — Execution date of U.S. Patent Application

Tokyo, Japan

Residence of second inventor

Masanobu Nakamura — June 25, 2003

Signature of second inventor — Date of this assignment

[illegible]

Kazuhiko NAKAMURA

Name of third inventor — Execution date of U.S. Patent Application

Osaka, Japan

Residence of third inventor

Signature of third inventor — Date of this assignment

Tomotaka YAGI

Name of fourth inventor — Execution date of U.S. Patent Application

Hyogo, Japan

Residence of fourth inventor

Signature of fourth inventor — Date of this assignment

Declan Patrick KELLY

Name of fifth inventor — Execution date of U.S. Patent Application

Eindhoven, The Netherlands

Residence of fifth inventor

Signature of fifth inventor — Date of this assignment

Wilhelmus Jacobus VAN GESTEL

Name of sixth inventor — Execution date of U.S. Patent Application

Heeze, The Netherlands

Residence of sixth inventor

Signature of sixth inventor — Date of this assignment

Sony [illegible]

FLH File No.

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NOW THEREFORE, in consideration of the sum of One Dollar ($1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

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Residence of first or sole inventor

Signature of first or sole inventor　　　Date of this assignment

Masanobu NAKAMURA

Name of second inventor　　　Execution date of U.S. Patent Application

Tokyo, Japan

Residence of second inventor

Signature of second inventor　　　Date of this assignment

Sony Ref: 03/0398 [illegible]

Kazuhiko NAKAMURA

Name of third inventor — Execution date of U.S. Patent Application

Osaka, Japan

Residence of third inventor

Kazuhiko Nakamura — June 30, 2003

Signature of third inventor — Date of this assignment

Tomotaka YAGI

Name of fourth inventor — Execution date of U.S. Patent Application

Hyogo, Japan

Residence of fourth inventor

Tomotaka Yagi — June 26, 2003

Signature of fourth inventor — Date of this assignment

Declan Patrick KELLY

Name of fifth inventor — Execution date of U.S. Patent Application

Eindhoven, The Netherlands

Residence of fifth inventor

Signature of fifth inventor — Date of this assignment

Wilhelmus Jacobus VAN GESTEL

Name of sixth inventor — Execution date of U.S. Patent Application

Heeze, The Netherlands

Residence of sixth inventor

Signature of sixth inventor — Date of this assignment

[illegible] P 396US

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Residence of first or sole inventor

Signature of first or sole inventor — Date of this assignment

Masanobu NAKAMURA

Name of second inventor — Execution date of U.S. Patent Application

Tokyo, Japan

Residence of second inventor

Signature of second inventor — Date of this assignment

Kazuhiko NAKAMURA

Name of third inventor — Execution date of U.S. Patent Application

Osaka, Japan

Residence of third inventor

Signature of third inventor — Date of this assignment

Tomotaka YAGI

Name of fourth inventor — Execution date of U.S. Patent Application

Hyogo, Japan

Residence of fourth inventor

Signature of fourth inventor — Date of this assignment

Declan Patrick KELLY

Name of fifth inventor — Execution date of U.S. Patent Application

Eindhoven, The Netherlands

Residence of fifth inventor

Declan Kelly — 25 July 2003

Signature of fifth inventor — Date of this assignment

Wilhelmus Jacobus VAN GESTEL

Name of sixth inventor — Execution date of U.S. Patent Application

Heeze, The Netherlands

Residence of sixth inventor

Wilhelmus Jacobus van Gestel — 28 July 2003

Signature of sixth inventor — Date of this assignment